

JPCA Show

52nd International Electronic
Circuits Exhibition

JEIP Microelectronics Show

37th ADVANCED ELECTRONICS
PACKAGING EXHIBITION

**JISSO
PROTEC**

24th Jisson Process Technology
Exhibition



SDGs Device Show



Connecting Devices to Devices

WIRE Japan Show

Electrical
/optical transmission technology



**Electronics
Component & Unit
Show**

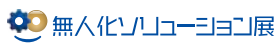
Japan Federation Of Electronic Parts Distributors And Dealers
Tokyo Electronics Appliances Wholesalers Association



E-Textile / Wearable



Smart Sensing



Unmanned Solution Exhibition



Edge Computing

INTERNATIONAL OPTOELECTRONICS EXHIBITION



interOpto



Imaging Japan



The Exhibition Guide

It all starts here! ~ Exhibition X ~

2023.5.31 Wed. → 6.2 Fri.

Tokyo Big Sight East Exhibition Halls

**The Total Solution Exhibition
for Electronic Equipment 2023**



Official Website

Applications will be accepted from October 17, 2022 (Mon.) 10:00 a.m. (JST)

Organizers: Japan Electronics Packaging and Circuits Association,
Japan Institute of Electronics Packaging, Japan Robot Association
Co-organizers: Electronic Device Industry News (Sangyo Times, Inc.), Electric Wire & Cable News (KOGYO TSUSHIN CO., LTD),
JTB Communication Design, Inc.
Japan Federation Of Electronic Parts Distributors And Dealers
Tokyo Electronics Appliances Wholesalers Association
SENKEN SHIMBUN CO., LTD., Optoelectronics Industry and Technology Development Association
Sponsor (tentative): Ministry of Economy, Trade and Industry

Overseas Cooperation:
World Electronic Circuits Council (WECC) Member Associates:
China Printed Circuit Association (CPCA),
European Institute of Printed Circuits (EIPC),
Hong Kong Printed Circuit Association (HKPCA),
IPC-Association Connecting Electronics Industries (IPC), Indian Printed Circuit Association (IPCA),
Electronic Industries Association of India (ELCINA), Korea Printed Circuit Association (KPCA),
Thailand Printed Circuit Association (THPCA),
Taiwan Printed Circuit Association (TPCA)

AEIS (Association of Electronic Industries in Singapore)
KPIA (Korea Packaging Integration Association)

As of Oct. 17, 2022

Comprehensive exhibition of technology embodying 5G/5G+, automobile, IoT/infrastructure (network, reusable energy, data center, etc.), robots, wearable, advanced optical system, etc.

- Highly specialized and focused
- Exhibition of large attendance from all over the world

Exhibition Outline

Our objective is to offer and propose technical information and contribute to the advancement of the electronic circuit industry and all related fields by presenting exhibitions of new contents and solutions related to the electronic circuits and packaging technologies used in all electronic / information and communication / control equipments, as well as sensors and E-Textiles (wearable technology) which have great potential for widespread use.

Exhibition Period	Wednesday, May 31 to Friday, June 2, 2023, 10:00 a.m. - 5:00 p.m.
Venue	Tokyo Big Sight East Exhibition Halls
Managed by	Japan Electronics Packaging and Circuits Association (JPCA)
Secretariat Office	JTB Communication Design, Inc.
Admission	1,000 Yen (including tax) * Free Admission for those who have pre-registered online.

Result of 2022

Venue	Tokyo Big Sight East Halls 4-6+Conference Tower
Exhibit scale	313 companies / 845 booths
Number of visitors	27,972 people

Exhibitions held inside the exhibition/relevant exhibits

Electronic circuits technology		High-density packaging technologies	Electronic Component Packaging Technologies	
 <p>JPCA Show 52nd International Electronic Circuits Exhibition</p> <ul style="list-style-type: none"> ● PWB Tech Finished Products, Design Technologies, Reliability and Inspection Technologies, Main Materials, Processing Technologies, Materials, and Equipment, Manufacturing Equipment, Environmental Systems, Distribution Systems ● Module JAPAN Module board / Module Board mounting / General technology for built-in parts (Finished Products / Related Products / Design / Reliability inspection / Materials/Functional materials / Related equipment / Related system) ● Flexible Printed Circuits Products Area General technology for Flexible Printed Circuits (Manufacturing) ● EMS Japan General contracted services related to EMS, Electronic electrical equipments, and Semiconductors <p>Organizer: Japan Electronics Packaging and Circuits Association</p>		 <p>Microelectronics Show 37th ADVANCED ELECTRONICS PACKAGING EXHIBITION</p> <p>General technology for implementation and electric technology (Materials / Circuit and Mounting design / High speed high frequency / Electromagnetic properties / Electronic parts / mounting / Optical circuit mounting / Environmental affinity implementation / Semiconductor Package / Micro mechatronics mounting technology / Related Manufacturing equipment)</p> <p>Organizer: Japan Institute of Electronics Packaging</p>	 <p>24th Jisso Process Technology Exhibition</p> <ul style="list-style-type: none"> ■ Electronic Component Placement Machines and related Equipment and Systems: electronic component placement machines (Mounter), electronic component insertion machines (Insertor), screen printers, soldering equipment (reflow oven), and dispensers ■ Packaging related Equipment and Systems: transfer systems, AGV, automatic warehouse, taping machines and materials, bulk feeders and other feeders, and automatic assembly machines, laser marking machine, cleaning equipment - cleaner ■ Semiconductor Packaging Machines and Systems: bonding equipment, flip chip packaging systems, COB systems ■ Industrial Robotics: handling robots, assembly robots, transport robots ■ Inspection/Test Equipment: automated optical inspection equipment, inspection/measuring equipment associated with semiconductor manufacturing ■ Packaging Design Systems: design tools, production optimizing software, and packaging programming equipment ■ Packaging Device Packaging Materials ■ Packaging Joining Systems - Solder/joining materials ■ High Frequency Compatible Devices, Components, and Materials ■ Environment related Devices and Materials <p>Organizer: Japan Robot Association</p>	
SDGs Materialization Technology		Electrical/optical transmission technology	Semiconductors and Electronic parts	Highly functional textile
 <p>SDGs Device Show</p> <ul style="list-style-type: none"> • Renewable energy related electronics • Power electronics related mounting / materials • Power semiconductors / power devices (IGBTs, MOSFETs, Bipolar transistor, etc.), various memories (S-RAM, D-RAM, etc.), semiconductor package, module with built-in parts, metal core printed wiring board, thermal solution, Solar cell batteries, batteries, hydrogen fuel, power electronics, various related devices, etc. <p>Co-organizers: Japan Electronics Packaging and Circuits Association, Electronic Device Industry News (Sangyo Times, Inc.)</p>		 <p>Connecting Devices to Devices WIRE Japan Show Electrical/optical transmission technology</p> <p>General transmission technology for using wire and cable (Industrial equipment / Electrical wire, cable and connector / Electric wire processing machine / Wiring material / Wire Harness / Measuring instrument for electric wire and cable / Various devices + D116 / Inspection technology / M2M transmission / Optical transmission)</p> <p>Co-organizers: Japan Electronics Packaging and Circuits Association, Cable News (KOGYO TSUSHIN CO., LTD)</p>	 <p>Electronics Component & Unit Show</p> <p>JEPF Japan Federation Of Electronic Parts Distributors And Dealers Tokyo Electronics Appliances Wholesalers Association</p> <p>General technology for solutions by Semiconductors and Electronic parts (Semiconductors / Electronic Devices / Sensors / Mechanical Devices / FA control equipments / Measuring instruments / Power Sources / IoT and M2M Solution / Manufacturing solution system)</p> <p>Co-organizers: Japan Federation Of Electronic Parts Distributors And Dealers, Tokyo Electronics Appliances Wholesalers Association</p>	 <p>E-Textile / Wearable</p> <p>E-Textile / Wearable</p> <p>A mix e-textile of electronic technology, fiber and clothing (General technology for smart textile, stretchable and wearable (Textile material / Conductive material / material / Knitting / weaving technology / Print marking technology / Films)</p> <p>Co-organizers: Japan Electronics Packaging and Circuits Association, SENKEN SHIMBUN CO., LTD.</p>
Sensor technology	Unmanned technology/ Unmanned Solution	Edge solution technology	Optical and next-generation applications / network systems	Image processing / sensing technology
 <p>Smart Sensing</p> <p>General technology for Sensor and Sensing System (Sensors, Sensor Nodes, Semiconductors, Parts and Devices, Electronics, Telecommunications Devices, Network Systems, Software, Data Platform, Power Sources, Other Related Devices, Technologies and Services)</p> <p>Co-organizers: Japan Electronics Packaging and Circuits Association, JTB Communication Design, Inc.</p>	 <p>無人化ソリューション展 Unmanned Solution Exhibition</p> <p>Unmanned technology/Unmanned Solution, Monitoring system/Remote control system /ADAS/Deep learning/Noncontact system /Touchless system/AR/Anomaly detection system/facial recognition system/AI etc.</p> <p>Co-organizers: Japan Electronics Packaging and Circuits Association, JTB Communication Design, Inc.</p>	 <p>Edge Computing</p> <p>Advantageous general edge solutions for areas such as low delay, high safety and low communication volume [Edge Application Areas] Automatic operation system / Factory Automation / Telemedicine / AR/VR / Smart city / Agritech / FinTech / Unmanned store, etc.</p> <p>Co-organizers: Japan Electronics Packaging and Circuits Association, JTB Communication Design, Inc.</p>	 <p>INTERNATIONAL OPTOELECTRONICS EXHIBITION InterOpto interOpto</p> <p>Optical devices for Automotive and in-vehicle / Manufacturing and production systems / Data centers / Long-distance communication / Healthcare and medical optical devices / AV and home appliances</p> <p>Organizer: Optoelectronics Industry and Technology Development Association (OITDA) Presented by: JTB Communication Design, Inc.</p>	 <p>Imaging Japan</p> <p>Various camera / sensor equipments / Image processing equipment / Image recognition / image understanding technology / Instrumentation / measurement technology / LiDAR</p> <p>Co-organizers: Japan Electronics Packaging and Circuits Association, JTB Communication Design, Inc.</p>

■ Comments from 2022 exhibitors on reasons for exhibiting and results

● Comments from exhibitors (excerpt from the exhibitor's questionnaire)

 There were many visitors that are in our target range making it a very fulfilling exhibition.

 Due to the COVID-19 pandemic, it was the first time we exhibited in three years, so we were quite anxious. However, it was a bigger turn-out than we had expected and made us realize the importance of in-person events. It was good to exhibit regardless of our anxieties.

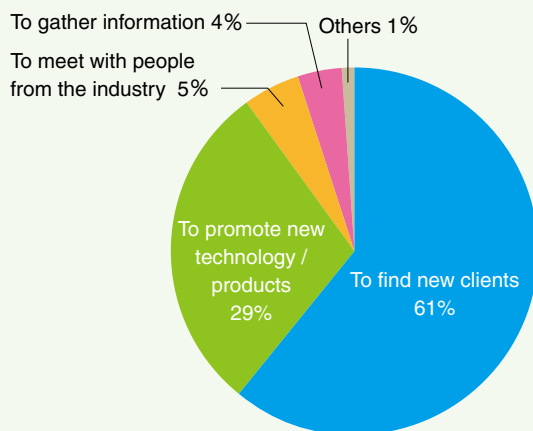
 The results (of exhibiting) were of higher quality than other exhibitions. We were able to hold deep discussions with visitors.

 The number of visitors to our booth was larger than we expected. We appreciated the addition of being able to acquire new leads from the online explanation of products.

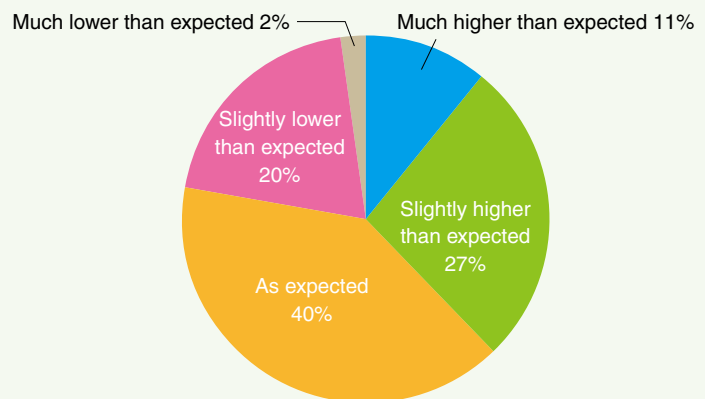
 It seemed that the visitors all had concrete purposes to visit.

 In order for small and medium size companies from non-major cities to meet with new clients, in-person exhibitions held in the Tokyo area are a necessity, so we hope that the exhibition will continue to be held in the future.

● Reasons for exhibiting



● Results of exhibiting



■ NEW “Exhibitors’ Interaction Event” to be held

An “Exhibitors’ Interaction Event” will be held during the exhibition period to promote interaction between exhibitors.

■ Companies in each field that are expected to participate

● Related to automobile:

ALPS ALPINE, TOKAI RIKI, STANLEY ELECTRIC, DENSO, Mitsubishi Electric, NISSAN MOTOR, TOYOTA MOTOR, Panasonic Industry, Panasonic Automotive Systems, NGK SPARK PLUG, NHK SPRING, NOK, PIONEER, MIRISE Technologies, AISIN, Marelli, NIWA CORP, Toyodensho, Asahi Denshi, TOYOTA, ALPINE MANUFACTURING, TAIYO KOGYO, NITTO KOGYO, NNP Electronics, Toyoda Gosei, JVCKENWOOD, YOKOWO, Hitachi Astemo, Yamaha Motor

● OA/Robotics:

Panasonic Connect, OMRON, Mitsubishi Electric, RICOH, Panasonic Industry, SANYO DENKI, Canon, ORIENTAL MOTOR, Toshiba Teli, PFU, JUKI, FUJI, KONICA MINOLTA, Yokogawa Manufacturing, YASKAWA Electric, RKC INSTRUMENT, Watanabe Electric Industry, NOHMI BOSAI, Azbil, KEYENCE, TAMURA CORPORATION, Watanabe Electric Manufacturing, RISO KAGAKU, KIKUSUI ELECTRONICS, COSEL, Magnescale, Togami Electric Mfg, Hitachi Industrial Equipment Systems, FUJI ELECTRIC, Yamaha Motor

● Related to information and communication:

Panasonic Connect, Canon, Huawei, Murata Manufacturing, Dai Nippon Printing, NEC, KYOCERA, KONICA MINOLTA, Toppan Printing, Panasonic, FURUNO ELECTRIC, Panasonic Industry, Oki Electric Industry, TOSHIBA, Sony, NIKON, VS Technology, FUJI ELECTRIC, Enplas, SUNCORPORATION, STANLEY ELECTRIC, TECHNOHORIZON, Hitachi Kokusai Electric, Sumitomo Electric Industries, TAIYO YUDEN, Edmund Optics Japan, MITSUMI ELECTRIC, Kyowa Electronic Instruments, Topre

● Related to AV and home electrical appliances:

Panasonic, Sony Global Manufacturing & Operations, Canon, Sony, Panasonic Connect, RICOH, CASIO COMPUTER, DAIKIN INDUSTRIES, Maxell, SONY GROUP, Audio-Technica, JANOME, Panasonic Holdings, LG Japan Lab, TOTO, TANITA, JVCKENWOOD, SIGMA, Mitsubishi Electric, TOA, Sharp, Panasonic Entertainment & Communication, CHOFU SEISAKUSHO, SMK, Audio-Technica Fukui, Samsung R&D Institute Japan, Panasonic Operational Excellence

● Related to medical equipment:

Olympus, RION, JEOL, NIKON, HORIBA, Canon Components, Topcon, Autosystem, TSUGAWA, MED-TECH, Gunmakioike, Terumo, Hamamatsu Photonics, A&D, DAITO, NAKANISHI, FORCE ENGINEERING, Fukuda Denshi, KOWA, Daiei Industry, TOA Electric Industrial, HIRAYAMA Manufacturing, Create Medic, PARAMOUNT BED, Universal Bio Research, ASAHI INTECC

● Related to aerospace:

TOKYO KEIKI, Topcon, Mitsubishi Electric, IHI, Panasonic Connect, Mitsubishi Heavy Industries, SMC, SANKYO DENSEI, NEC Network and Sensor Systems, RIKO DENKI, ANA SKY BUILDING SERVICE, MSR, NTT e-Drone Technology, Solaseed Air, Tyco Electronics Japan, SPC ELECTRONICS, TOSHIBA ELECTRO-WAVE PRODUCTS, Moog JAPAN, Green Hills Software, NEC Space Technologies, Alouette Technology, FIRSTVILLAGE, Kokushikan University, NIKKEI ELECTRONIC INSTRUMENTS

● Related to semiconductor device:

Toppan Printing, KYOCERA, TDK, Dai Nippon Printing, TAIYO YUDEN, YITOA MICRO TECHNOLOGY, Sony Semiconductor Solutions, SEMITEC, Panasonic Connect, Sanken Electric, ROHM, Mitsubishi Electric, NAITO DENSEI KOGYO, KEL, Japan Aviation Electronics Industry, Panasonic Industry, HIROSE ELECTRIC, TAMURA CORPORATION, CONNECTEC JAPAN, FUJI ELECTRIC, Analog Devices, KYOTO SEMICONDUCTOR, FUJI, I-PEX, SMK, KIOXIA, Nisshinbo Micro Devices, Yamaha Motor, Yamaha Robotics Holdings

● Optical technology:

Ushio, Panasonic, NIKON, STANLEY ELECTRIC, NICHIA, Dai Nippon Printing, HOYA, VS Technology, Anritsu, Edmund Optics Japan, Enplas, Optoquest, Gigaphoton, REVOX, KYOCERA, Furukawa Electric, NTT Electronics, CCS, CITIZEN ELECTRONICS, Spectra-Physics, SONY GROUP, Mitsubishi Electric, ASAHI RUBBER, HAMAI ELECTRIC LAMP

● Electronic circuit board

Panasonic Connect, SIIX, PASSCON, SUMITRONICS, ZUKEN, ASTI, FUJI, ADVANTEC, PULAX, Tokyo Drawing, JAPAN CIRCUIT, Asahi Denshi, M D SYSTEMS, Oki Electric Industry, KYOCERA, HIKARI TRADING, MITSUBISHI ELECTRIC ENGINEERING, TOA ELECTRONICS, Canon, Sony Global Manufacturing & Operations, Mitsubishi Electric

● Other:

YUSEN LOGISTICS, YAMATO TRANSPORT, YAMATO BOX CHARTER, EAST JAPAN RAILWAY TRADING, ANA SKY BUILDING SERVICE, East Japan Railway, Nishi - Nippon Railroad, JR East Rail Car Technology & Maintenance, JR East Consultants, East Nippon Expressway, NEXCO WEST Innovations, ALL NIPPON AIRWAYS TRADING, JR EAST STARTUP

Exhibition Fee

Category		1 booth/9m ² *Tax included
Non-Members		Yen 451,000
Members ^{*1}	Regular	Yen 385,000
	Increased booth discount ^{*2}	50% off the exhibition fees of the increased booths

*1 Members of the following associations

WECC Member Associations (CPCA, EIPC, ELCINA, HKPCA, IPC, IPCA, KPCA, THPCA, TPCA)
AEIS, KPIA

*2 Increased booth discount: 50% of the exhibition fees will be discounted for the number of booths increased from the maximum number exhibited from 2018 onwards.

* Size of a booth is 9m² (3m × 3m).

* Booth construction, cleaning, electricity, water Supply, etc. is not included in the exhibition fee.

How to apply (From October 17, 2022 (Mon.) 10:00a.m (JST))

Please apply online on our website. (www.jpccashow.com)

Applications will be accepted from October 17, 2022 (Mon.) 10:00a.m (JST)

If you use the Application Form, please apply by e-mail or FAX.

Please select the exhibition based on your products, technologies or services and carefully read the "Exhibition Regulations" on the back of the Application Form.

For the exhibition which has the exclusive application form, the relevant exhibition regulations shall be applied.

We will send you an invoice after receiving the Application Form, so please transfer the fee to our account by the due date noted on the invoice (In principle, transfer before the exhibition). The invoice can be downloaded from the exhibitor portal.

Deadline

Tuesday, February 28, 2023

If all spaces are reserved before the deadline, the application will no longer be accepted.

Cancellation charges

If an exhibit is cancelled to suit the exhibitor's circumstances, cancellation charges (full or partial fees) shall apply as below.

Date of receipt of written notice of cancellation	Cancellation charges
Until Tuesday, February 28, 2023	30% of booth fees
Wednesday, March 1 – Friday, March 31, 2023	50% of booth fees
Saturday, April 1 – Sunday, April 30, 2023	70% of booth fees
From Monday, May 1, 2023 onward	100% of booth fees

Schedule prior to the Exhibition (Tentative)

2022 October	2023 February	March	April	May	June
<p>▲</p> <p>October 17 (Mon.) 10:00 – Exhibition application begins</p>	<p>▲</p> <p>February 28 (Tue.) Exhibitor application deadline</p>	<p>▲</p> <p>Early March Exhibitor Manual available</p> <p>▲</p> <p>Mid-March Booth Location Selection Meeting</p>	<p>▲</p> <p>Early April Sending Invitations Visitor Registration begins</p>	<p>May 29 (Mon.) - 30 (Tue.) Installation period</p>	<p>May 31 (Wed.) - June 2 (Fri.) Exhibition open</p> <p>* Immediate removal on the last day</p>
<p>Mid-March onwards Submission of necessary forms</p>					

● Safety measures and policies to be taken by organizers

We will take measures to reduce spread of COVID-19 among participants, organizers and other parties involved in the exhibition, and hold the Exhibition with attention to safety.

From now on, in consideration of the policies and requests of the Japanese government, relevant ministries and agencies, and local governments, we will plan and implement the exhibition in cooperation and consultation with the facility side.

● In the event of cancellation of the Exhibition

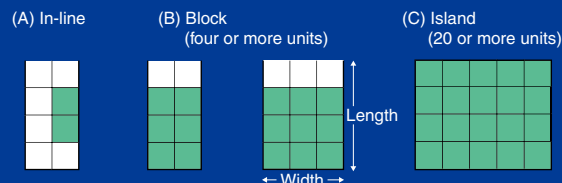
If we decide to cancel the Exhibition due to COVID-19, we will refund the total exhibition fee. * For details, please see the Exhibition Regulations.

**Please refer to the following websites for the most recent information.

> Border enforcement measures to prevent the spread of novel coronavirus (COVID-19) (Ministry of Foreign Affairs of Japan website): https://www.mofa.go.jp/ca/fna/page4e_001053.html

> Situation Report in Japan (Ministry of Health, Labour and Welfare website): https://www.mhlw.go.jp/stf/covid-19/kokunainohasseijoukyou_00006.html#1-1

Booth type



*In some cases, it may not be possible to prepare the requested booth type.

*Requests for a corner booth are not accepted.

Assignment of Booth Locations

Booths will be assigned at the Booth Location Selection Meeting (scheduled for the middle of March, 2023).

As a rule, exhibitors will be able to choose their booth locations on a first-come-first-served basis.

Details will be made available in the rules and regulations to be made public from 10:00 a.m. October 17th.

Exhibitor Support Program Option

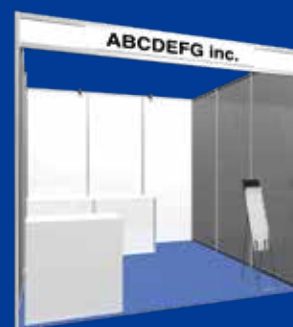
Promotion services will provide an opportunity to increase your presence at the exhibition.

Package booth

● 1 booth / basic plan

Price: 82,500 Yen (Tax included)

This plan includes the minimum necessary booth fixtures and fittings, power supply and carpet.



Managed by

Japan Electronics Packaging and Circuits Association (JPCA)

Kairo Kaikan 2F, 3-12-2, Nishigikita, Suginami-ku, Tokyo 167-0042

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Official Website